



RevB:
 1) implemented bootstrap resistor R5=3.320ohm to reduce overshoot
 2) adjusted RC snubber network to new FET selection,
 R9 = 10hm, C12 = 2.2nF

- ASSEMBLY:
- 1) replace C1..C3, C6, C7
 - 2) R4 OPEN, C10 =10nF (TPS53014)
 - 3) assemble C8
 - 4) replace L1, geometry will not meet pattern
 - 5) R2, R5 = 0 Ohm
 - 6) R7, R9 = 2.21 Ohm
 - 7) replace Q1, Q2
 - 8) R10 = 6.81kOhm, CS treshold to 50mV across Q2
 - 9) R1 = 6.81 kOhm, R11 = 150 Ohm, set Vout to 1.0V

NOTES:
 1) built on EVM PWR 126
 1) NOT POPULATED

Texas Instruments

Title 1V @ 12Amps w/ TPS53014		
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